



Docket No.: 1155-0271P
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Masahiro SAWADA et al.

Application No.: 10/607,519

Confirmation No.: 6031

Filed: June 27, 2003

Art Unit: 1711

For: POLYAMIDE RESIN COMPOSITION AND
MOLDED ARTICLE THEREOF

Examiner: A. L. Woodward

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enter
AW
7/05*

AMENDMENT AFTER FINAL ACTION (37 C.F.R. SECTION 1.116)

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated March 7, 2005, finally rejecting claims 1-6, the period for reply being extended one (1) month to July 7, 2005, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.